

Application Data Sheet

Application Information

Application Type:: Regular
Subject Matter:: Utility
Title:: Composite Lid For Land Grid Array
(LGA) Flip-Chip Package Assembly
Attorney Docket Number:: TI-35061 (1962-07300)
Request for Early Publication?:: No
Request for Non-Publication?:: No
Suggested Drawing Figure:: 1
Total Drawing Sheets:: 4
Small Entity?:: No

Applicant Information

Applicant Authority type:: Inventor
Primary Citizenship Country:: Taiwan
Status:: Full Capacity
Given Name:: Tz-Cheng
Family Name:: CHIU
City of Residence:: Plano
State or Province of Residence:: TX
Country of Residence:: US
Street of mailing address:: 3620 Dripping Springs Drive
City of mailing address:: Plano
State or Province of mailing address:: TX
Country of mailing address:: US
Postal or Zip Code of mailing address:: 75025

Correspondence Information

Correspondence Customer Number:: 23494

Representative Information

Representative Customer Number:: 23494

Assignee Information

Assignee name::	Texas Instruments Incorporated
Street of mailing address::	P.O. Box 655474, MS 3999
City of mailing address::	Dallas
State or Province of	
mailing address::	TX
Country of mailing	
address::	US
Postal or Zip Code of	
mailing address::	75265